L Number	Hits	Search Text	DB	Time stamp
2	73863	"heat sink"	USPAT;	2004/09/19 13:34
			US-PGPUB;	
			EPO; JPO;	
		•	DERWENT;	
3	0400	Umadial musicational	IBM_TDB	2004/00/10 12 24
3	9409	"radial projections"	USPAT; US-PGPUB;	2004/09/19 13:34
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
4	35	"heat sink" and "radial projections"	USPAT;	2004/09/19 13:52
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
5	160	cylindrical heat sink"	IBM_TDB USPAT;	2004/09/19 13:52
3	100	Cylindrical neac Sink	US-PGPUB;	2004/09/19 13:52
			EPO; JPO;	'
			DERWENT;	
,			IBM TDB	
6	92	"rectangular heat sink"	USPĀT;	2004/09/19 13:52
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
7	8	"conical heat sink"	IBM_TDB USPAT;	2004/09/19 13:55
,		Conical near Sink	US-PGPUB;	2004/09/19 13:55
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
8	11	"tapered heat sink"	USPĀT;	2004/09/19 14:00
			US-PGPUB;	
	·		EPO; JPO;	
			DERWENT;	
9	232	"heat sink" near3 "electrically insulated"	IBM_TDB USPAT;	2004/09/19 14:13
		near bink hears creetifearry insurated	US-PGPUB;	2004/09/19 14.15
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
10	140	"heat sink" near1 "electrically insulated"	USPAT;	2004/09/19 14:14
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
11	618	(237/12.3r).CCLS.	USPAT;	2004/09/19 14:39
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1.0		Habara (C. N.) a Narah ada N	IBM_TDB	000110011
12	0	"shape of the heat sink"	USPAT;	2004/09/19 14:39
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
13	118	"heat sink shape"	USPAT;	2004/09/19 14:40
		_	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	F C1	(210/200) CCLC	IBM_TDB	2004/00/15 55 55
-	561	(219/209).CCLS.	USPAT;	2004/09/17 16:06
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	80	transistor and ((219/209).CCLS.)	USPAT;	2004/09/13 16:43
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
L	<u></u>		IBM TDB	

481 ((219/209).CCLS.) not (transistor and (USPAC) ((219/209).CCLS.))					
- 2 ("6348672").PN. DERMENT; THM TOB USPAT; USPACEOUS; ERO, JPO; DERWENT; ERO, J	-	481	((219/209).CCLS.) not (transistor and ((219/209).CCLS.))		2004/09/13 16:52
- 2 ("6348672").PN. USPAT; USPACEUB; EPO; JPO; DERWENT; ISPACEUB; EPO; JPO				DERWENT;	
- 5 ("3139515" "3801278" "4216371" USPAT IEM TOB COM/09/13 16:53		2	/#.62.40.67.2#\ DNI		2004/00/12 17:05
- 5 ("3139515" "3801278" "4216371" USPAT	_	2	(0340072).FN.		2004/09/13 17:03
- 5 ("3139515" "3801278" "4216371" USPAT USPAT 2004/09/13 16:53 2004/09/13 16:53 2004/09/13 16:53 2004/09/13 16:53 2004/09/13 16:53 2004/09/13 16:53 2004/09/13 16:53 2004/09/13 16:56 2004/09/13 16:53 2004/09/13 16:56 2004/09/14 09:06 2004/09/14 09:07 2004/09/14 09:0					
- 0 6348672.URPN 0 648672.URPN 0 648672.URPN 0 648672.URPN 0 648672.URPN 0 1966 (165/80.3).CCLS 1 1978 (219/203,530,540).CCLS 1 1978 (219/202,530,540).CCLS 1 1 "power transistor" and (237/12.3r).CCLS.) - 1 101 ((165/80.3).CCLS.) and "power transistor" - 1 101 ((165/80.3).CCLS.) and "power transistor" - 1 1074 (361/719).CCLS.) and "power transistor" - 1 1074 (361/719).CCLS.) and ("power transistor" us-perus, percy jec, jec, jec, jec, jec, jec, jec, jec,					1
- 0 6 4386444" ["53.0030").PN 2311 "power transistor" and "heat sink" USPAT USPAT;				IBM TDB	
- 0 6348672.URNN. USPAT; USPAT	-	. 5	("3139515" "3801278" "4216371"	USPAT	2004/09/13 16:53
- 2311 "power transistor" and "heat sink" USPAT; Sold (165/80.3).CCLS. USPAT; U					
- 325556 "circuit board" US-PGPUB; EPO; JFO; DERNENT; IBM TOB USPAT; USPA	-			*	
- 32556 "circuit board"	-	2311	"power transistor" and "neat sink"		2004/09/13 17:08
- 325556 "circuit board" DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO;					
- 2353 (165/80.3).CCLS. IRM TDB USPAT; USP					
- 2353 (165/80.3).CCLS. USPĀT; US-PGCPUS, EPO; JPO; DERMENT; IBM TDB USPĀT; US-PGCPUS, EPO; JPO; DERMENT; IBM T				•	
EPG, JPG, DENWENT; IBM TDB USPAT; US-PGPUB; EPG, JPG) DENWENT; IBM TDB USPAT; US-PGPUB; EPG, JPG) DENWENT; IBM TDB USPAT; US-PGPUB; EPG, JPG, DERWENT; IBM TDB USPAT; US-PGPUB; EPG, JPG, JPG, JPG, DERWENT; IBM TDB USPAT; US-PGPUB; EPG, JPG, JPG, DERWENT; US-PGPUB; EPG, JPG, JPG, DER	-	325556	"circuit board"		2004/09/13 17:08
- 2353 (165/80.3).CCLS. DERMENT; IEM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IEM TDB USPAT;					
TIM TD					
- 2353 (165/80.3).CCLS. USPĀT; US-PCPUB; EPO; JPO; DERMENT; IBM TDB USPĀT; US-PCPUB; EPO; JPO; DERMENT; US-PCPUB; EPO; JPO; DERMEN					
- 1966 (219/203,530,540).CCLS. US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERMENT; US-PGPUB; E	_	2353	(165/80.3).CCLS.		2004/09/14 09:06
- 1966 (219/203,530,540).CCLS. USPAT; USPGUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT; USPACHUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT; USPACHUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPACHUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT; USPACHUB; EPO; JPO; DERWENT; IBM TDB		2333	(1207,00.07.0000.		
- 1966 (219/203,530,540).CCLS. DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT			,	1	
- 1966 (219/203,530,540).CCLS. USPĀT; US-PGPUB; EPG, JPG, DERWENT; IBM TDB USPĀT; US-PGPUB; EPG, JPG, DERWENT; IBM TDB USPĀT; US-PGPUB; EPG, JPG; DERWENT;					
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DE					
- 1978 (219/202,530,540).CCLS. - 1978 (219/202,530,540).CCLS. - 21 "power transistor" and (1297/12.3r).CCLS.) - 21 "power transistor" and (1237/12.3r).CCLS.) - 1 "power transistor" and (1237/12.3r).CCLS.) - 101 ((165/80.3).CCLS.) and "power transistor" - 101 ((165/80.3).CCLS.) and "power transistor" - 1074 (361/719).CCLS. - 1074 (361/719).CCLS. - 1074 (361/719).CCLS.) and "heat sink") and "circuit board" - 1075 ("power transistor" and "heat sink") and "circuit board" - 1076 ("sparse transistor" and "heat sink") and "circuit board" - 1077 ("sparse transistor" and "heat sink") and "circuit board" - 1078 ("sparse transistor" and "heat sink") and "circuit board" - 1079 ("sparse transistor" and "heat sink") and "circuit board" - 1079 ("sparse transistor" and "heat sink") and "circuit board" - 1079 ("sparse transistor" and "heat sink") and "circuit board" - 1079 ("sparse transistor" and "sparse transistor" and "heat sink") and "circuit board" - 1079 ("sparse transistor" and "sparse transistor" and "heat sink") and "circuit board" - 1079 ("sparse transistor" and "sparse transistor" and "heat sink") and "circuit board" - 1079 ("sparse transistor" and "sparse transistor" and "	_	1966	(219/203,530,540).CCLS.		2004/09/14 09:07
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT				1	
IBM TDB					
- 1978 (219/202,530,540).CCLS. USPĀT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERMENT;				· ·	
EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM	_	1978	(219/202,530,540).CCLS.		2004/09/14 09:07
- 21 "power transistor" and ((219/202,530,540).CCLS.) - 1 "power transistor" and ((237/12.3r).CCLS.) - 1 "power transistor" and ((237/12.3r).CCLS.) - 101 ((165/80.3).CCLS.) and "power transistor" - 101 ((165/80.3).CCLS.) and "power transistor" - 1074 (361/719).CCLS. - 793 ("power transistor" and "heat sink") and "circuit board" - 40 ((361/719).CCLS.) and (("power transistor" US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM				1	
- 21 "power transistor" and ((219/202,530,540).CCLS.) - 1 "power transistor" and ((237/12.3r).CCLS.) - 1 "power transistor" and ((237/12.3r).CCLS.) - 101 ((165/80.3).CCLS.) and "power transistor" - 101 ((165/80.3).CCLS.) and "power transistor" - 1074 (361/719).CCLS. - 793 ("power transistor" and "heat sink") and "circuit board" - 40 ((361/719).CCLS.) and (("power transistor" uspar: us					
- 21 "power transistor" and ((219/202,530,540).CCLS.) - 1 "power transistor" and ((237/12.3r).CCLS.) - 1 "power transistor" and ((237/12.3r).CCLS.) - 101 ((165/80.3).CCLS.) and "power transistor" - 1074 (361/719).CCLS. - 793 ("power transistor" and "heat sink") and "circuit board" - 40 ((361/719).CCLS.) and (("power transistor" and "heat sink") and "circuit board") - 40 ((361/719).CCLS.) and (("power transistor" and "heat sink") and "circuit board") - 2004/09/14 09:13 2004/09/14 09:13 2004/09/14 09:13 2004/09/14 09:46 2004/09/14 10:10 2004/09/14 10:10 2004/09/14 10:11 2004/09/14 10:11 2004/09/14 10:11 2004/09/14 10:11 2004/09/14 10:11					
Continue	_	21	 "power transistor" and		2004/09/14 09:07
- 1 "power transistor" and ((237/12.3r).CCLS.) - 101 ((165/80.3).CCLS.) and "power transistor" - 101 ((165/80.3).CCLS.) and "power transistor" - 1074 (361/719).CCLS. - 793 ("power transistor" and "heat sink") and "circuit board" - 40 ((361/719).CCLS.) and (("power transistor" and "heat sink") and "circuit board") - 40 ((361/719).CCLS.) and (("power transistor" and "heat sink") and "circuit board") - 5004/09/14 10:10 - 1074 (361/719).CCLS.) and (("power transistor" and "heat sink") and "circuit board") - 1074 (361/719).CCLS.) and (("power transistor" and "heat sink") and "circuit board") - 1074 (361/719).CCLS.) and (("power transistor" and "heat sink") and "circuit board")					
- 1 "power transistor" and ((237/12.3r).CCLS.) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EP					
- 1 "power transistor" and ((237/12.3r).CCLS.) USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; ISPOPGUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;					
US-PGPUB; EPC; JPC; DERWENT; IBM_TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; US-PGPUB; EPC; JPC; DERWENT; US-PGPUB; EPC; JPC; DERWENT; US-PGPUB; EPC; JPC; DERWENT;		1	"		2004/00/14 00:12
EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM	_		power transistor and ((237/12.31).ccls.)		2004/09/14 09.13
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT;					
- 101 ((165/80.3).CCLS.) and "power transistor" USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB;					
US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; ISO; DERWENT; ISO; DERWENT; ISO; DERWENT; ISO; JPO; DERWENT; JPO; JPO; JPO; JPO; JPO; JPO; JPO; JPO					
EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB	_	101	((165/80.3).CCLS.) and "power transistor"	1	2004/09/14 09:13
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;			·	1	
- 1074 (361/719).CCLS. IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;					
- 1074 (361/719).CCLS. USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;					
- 793 ("power transistor" and "heat sink") and "circuit board" 40 ((361/719).CCLS.) and (("power transistor" and "heat sink") and "circuit board") 40 (361/719).CCLS.) and "circuit board")	_	1074	(361/719).CCLS.	USPĀT;	2004/09/14 09:46
- 793 ("power transistor" and "heat sink") and "circuit board" 40 ((361/719).CCLS.) and (("power transistor" and "heat sink") and "circuit board") 40 (361/719).CCLS.) and "circuit board")					
- Tys ("power transistor" and "heat sink") and "circuit board" 40 ((361/719).CCLS.) and (("power transistor" and "heat sink") and "circuit board") 40 (361/719).CCLS.) and "circuit board")					
- 793 ("power transistor" and "heat sink") and "SPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((361/719).CCLS.) and (("power transistor" and "heat sink") and "circuit board") 40 ((361/719).dcls.) and "circuit board") 40 (361/719).dcls.) and "circuit board") 40 (Jegy Epo; JPO; DERWENT; DERWENT; DERWENT;	1			1	
"circuit board" "Circuit board" US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((361/719).CCLS.) and (("power transistor" and "heat sink") and "circuit board") US-PGPUB; EPO; JPO; DERWENT; DERWENT;	_	793	("power transistor" and "heat sink") and		2004/09/14 10:10
DERWENT; IBM_TDB USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT; DERWENT; DERWENT; US-PGPUB; EPO; JPO; DERWENT;				P.	
- 40 ((361/719).CCLS.) and (("power transistor" uS-PGPUB; and "heat sink") and "circuit board") US-PGPUB; EPO; JPO; DERWENT;		1			
- 40 ((361/719).CCLS.) and (("power transistor" USPAT; 2004/09/14 10:11 and "heat sink") and "circuit board") US-PGPUB; EPO; JPO; DERWENT;					
and "heat sink") and "circuit board") US-PGPUB; EPO; JPO; DERWENT;		1.0	//261/710) CCIC) ////		2004/00/14 10-11
EPO; JPO; DERWENT;	-	40			2004/09/14 10:11
DERWENT;			and heat Sink , and Circuit board ,	1	
IBM_TDB					
l				IBM TDB	

-	1034	((361/719).CCLS.) not (("power transistor"	USPAT;	2004/09/14 10:23
		and "heat sink") and "circuit board")	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	("20040129695").PN.	USPAT;	2004/09/14 10:43
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	635		USPAT;	2004/09/14 10:43
		transistor" and "heat sink") and "circuit	US-PGPUB;	
		board")) and hole	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	10	("5473510" "5671121" "5825625"	USPAT	2004/09/14 11:01
		"5990550" "6181567" "6229216"		
		"6286208" "6366467" "6392296"		
		"6407924").PN.		
_	2		USPAT;	2004/09/17 16:19
_	2	(0434723).IN.	US-PGPUB;	2004/03/17 10:13
			EPO; JPO;	
			DERWENT;	
		H0000011404H	IBM_TDB	2004/00/17 16:20
-	4	"2002011484"	USPAT;	2004/09/17 16:20
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	0004/00/15 16 01
_	3	"2001050843"	USPAT;	2004/09/17 16:21
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	"20010050843"	USPAT;	2004/09/17 16:21
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	("6392207").PN.	USPAT;	2004/09/17 16:25
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	3086	"heater block"	USPAT;	2004/09/17 16:25
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
l _	26554	"power transistor"	USPĀT;	2004/09/17 16:25
	20004	ponor oranorous	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			IBM TDB	
	23	"heater block" and "power transistor"	USPAT;	2004/09/17 16:26
-	23	neater brock and power transfator	US-PGPUB;	2004/05/11 10.20
			1	
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	